

3. (Original) The electronic device of claim 1, wherein the connector comprises a laminate material.

4. (Original) The electronic device of claim 3, wherein the laminate material comprises:

a core;

a dielectric material surrounding the core; and

a solder mask.

5. (Original) The electronic device of claim 4, wherein the laminate further includes a plated through hole.

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6. (Amended) The electronic device of claim 4, further including a connection between at least one contact on the first surface and at least one contact on the second surface.

7. (Amended) The electronic device of claim 6, further including a ground shield over the connection.

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8. (Original) The electronic device of claim 4, wherein the core comprises a material selected from the group consisting of: copper-invar-copper, copper, stainless steel, nickel, iron and molybdenum.

9. (Original) The electronic device of claim 4, wherein the dielectric material comprises polyimide.
10. (Original) The electronic device of claim 1, wherein the contacts comprise ball grid array connections.
11. (Original) The electronic device of claim 1, wherein the first substrate comprises a chip package.
12. (Original) The electronic device of claim 1, wherein the second substrate comprises a printed circuit board.
13. (Original) The electronic device of claim 1, further comprising a stiffener frame attached to the connector.
14. (Original) The electronic device of claim 13, wherein the stiffener frame is adhesively attached to the connector.
15. (Original) The electronic device of claim 13, wherein the stiffener frame surrounds a perimeter of the connector.
16. (Original) The electronic device of claim 13, wherein the stiffener frame is removably

attached to the connector.

17. (Original) The electronic device of claim 13, wherein the stiffener frame is attached to a surface of the connector.

18. (Original) The electronic device of claim 13, wherein the stiffener frame comprises a material selected from the group consisting of: plastic, metal and ceramic.

19. (Original) The electronic device of claim 13, wherein the stiffener frame comprises a heat sink.

20. (Amended) A connector system, comprising:

A3  
a flexible substrate;

a plurality of contacts on a first surface of the substrate; and

a plurality of contacts on a second surface of the substrate, wherein the contacts on the first surface of the substrate are alternatingly off-set from the contacts on the second surface of the substrate.

Sub B3  
21. (Original) The connector system of claim 20, wherein the flexible substrate comprises a laminate material.

22. (Original) The connector system of claim 21, wherein the laminate material comprises:

a core;

a dielectric material surrounding the core; and

a solder mask.

23. (Original) The connector system of claim 22, wherein the laminate material further includes a plated through hole.

24. (Amended) The connector system of claim 22, further including a connection between at least one contact on the first surface and at least one contact on the second surface.

25. (Amended) The connector system of claim 22, further including a ground shield over the connection.

26. (Original) The connector system of claim 22, wherein the core comprises a material selected from the group consisting of: copper-invar-copper, copper, stainless steel, nickel, iron and molybdenum.

27. (Original) The connector system of claim 22, wherein the dielectric material comprises polyimide.

28. (Original) The connector system of claim of 20, wherein the contacts comprise ball grid array connections.

29. (Original) The connector system of claim 20, further including a stiffener frame.

30. (Original) The connector system of claim 29, wherein the stiffener frame is removably attached to the flexible substrate.

31. (Amended) A method of forming an electronic device, comprising:

AS  
providing a flexible connector having a plurality of alternating contacts on a first surface and a second surface of the flexible connector; and  
attaching the flexible connector between a first substrate and a second substrate via the contacts.

Sub 34  
32. (Original) The method of claim 31, wherein the flexible connector comprises a laminate material.

33. (Original) The method of claim 31, wherein the contacts comprises ball grid array connections.

34. (Original) The method of claim 31, wherein select contacts on the first surface of the flexible connector are off-set from select contacts on the second surface of the flexible connector.

35. (Original) The method of claim 31, wherein the first substrate comprises a chip package.

36. (Original) The method of claim 31, wherein the second substrate comprises a printed circuit board.

37. (Amended) A method of forming an electronic device, comprising:

providing a first substrate;

providing a second substrate;

providing a flexible connector having a plurality of alternating contacts on a first surface and a second surface of the connector; and

attaching the contacts on the first surface of the connector to the first substrate and the contacts on the second surface of the connector to the second substrate.

38. (Original) The method of claim 37, wherein the first substrate comprises a chip package.

39. (Original) The method of claim 37, wherein the second substrate comprises a printed circuit board.

40. (Original) The method of claim 37, wherein the flexible connector comprises a laminate material.

41. (Original) The method of claim 37, wherein the contacts comprise ball grid array connections.

Please add the following new claims.

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42. (New) A method of forming an electronic device, comprising:

providing a flexible connector having a plurality of alternating contacts on a first surface and a second surface of the flexible connector, and a stiffener frame surrounding a perimeter edge of the flexible connector; and

attaching the flexible connector between a first substrate and a second substrate via the contacts.

43. (New) A connector system, comprising:

a flexible substrate; and

a plurality of contacts formed on a first surface and a second surface of the substrate, wherein the contacts are alternatingly off-set by a width of the contacts.

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#### REMARKS

Claims 1-43 are pending in this application. By this amendment, claim 2 has been canceled, claims 1, 6, 7, 20, 24, 25, 31 and 37 have been amended and new claims 42 and 43 have been added. Reconsideration and allowance in view of the amendments and the following remarks are respectfully requested.

The specification is objected to as failing to provide proper antecedent basis for claimed subject matter. By this amendment claims 6-7 and 24-25 have been amended for clarification.

Claims 1-4, 8, 10-12, 20-22, 26, 28 and 31-41 are rejected under 35 U.S.C. §102(b) as being anticipated by Appelt *et al.* (US 5,900, 675, hereinafter "Appelt"). Claims 5-7 and 23-25